

RH4Z2501-KIT – HW revision 3

Hardware application note

Introduction

This document explains the hardware design of the RH4Z2501-KIT, its main features and the necessary hardware setup to implement an IO-link device.

Target Device

RH4Z2501: IO-Link transceiver with integrated protection

Contents

1. Overview	3
1.1 RH4Z2501 Features	3
1.2 Kit Contents	3
1.3 RH4Z2501-KIT Capabilities.....	4
2. Getting Started	4
2.1 System Block Diagram	4
2.2 Default Board Configuration	5
3. RH4Z2501-KIT Components	5
3.1 Power Requirements	5
3.1.1 Power Supply Options	5
3.1.2 Voltage regulation Options	6
3.1.3 IO Voltage operation	6
3.2 Signal Sensor Conditioner: ZSSC3281	6
3.2.1 Enable I2C communication	6
3.2.2 JTAG/SWD Connector	6
3.2.3 AFE circuit	6
3.2.4 Oscillator.....	6
3.3 Commutation Switches.....	7
3.3.1 SW1 – Rx/D Signal selection	7
3.3.2 SW2 – Tx/D Signal selection.....	7
3.3.3 SW3 – TxEN Signal selection	7
3.3.4 SW4 – OWI/D Signal selection.....	7
3.3.5 SW1 – /WU Signal selection	7
3.4 LEDs.....	8
3.4.1 Power status.....	8
3.4.2 SSC status.....	8
3.4.3 IO-link communication status	8

Revision History 9

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products.... 1

Notice 1

1. Overview

1.1 RH4Z2501 Features

The RH4Z2501-KIT is an Evaluation Board for the RH4Z2501 Renesas silicon solution that implements an IO-Link device. The board also integrates an Advanced ARM based Sensor Signal Conditioner: ZSSC3281.

The main purpose of the RH4Z2501-KIT is to enable the communication between the user and the RH4Z2501 device with the GUI (Graphical User Interface). The RH4Z2501_Evaluation_SW establishes the communication via a USB port (configured as a virtual COM port) to the SSC Communication Board (CB). The microcontroller on the SSC CB interprets these commands, converts them according to the digital interface (I2C, SPI or OWI), and build the frame for to the RH4Z2501 and ZSSC3281 mounted on RH4Z2501 EVB.

The RH4Z2501 offers the following features:

- Voltage range from 9V to 36V
- Over voltage peak robustness of +/-60V
- Configurable driver output current 50mADC to 600mA DC
- Rdson of less than 2.5Ohm
- Adjustable driver slew rate
- Integrated Wake-Up detection
- MCU assisted Wake-up generation (typ. 600mA)
- OWI digital communication and calibration interface
- Integrated Linear Voltage Regulators 3.3V and 5V
- Ambient Temperature range -40°C ... 125°C
- Glitch filter for receiver
- Integrated Protection
 - +/-1.25kV/2.5A(peak) surge protection for VDD, CQ, GND (8/20 µs pulse acc. IEC xyz)
- Reverse polarity protection for VDD, CQ, GND
- On-chip diagnostics:
 - Over temperature detection
 - Supply voltage monitor
 - Broken chip detection

For more information, please refer to the RH4Z2501 Datasheet.

1.2 Kit Contents

RH4Z2501 Evaluation Board - RH4Z2501-KIT

SSC Communication Board - SSCCOMMBOARDV4P1C

USB Cable

1.3 RH4Z2501-KIT Capabilities

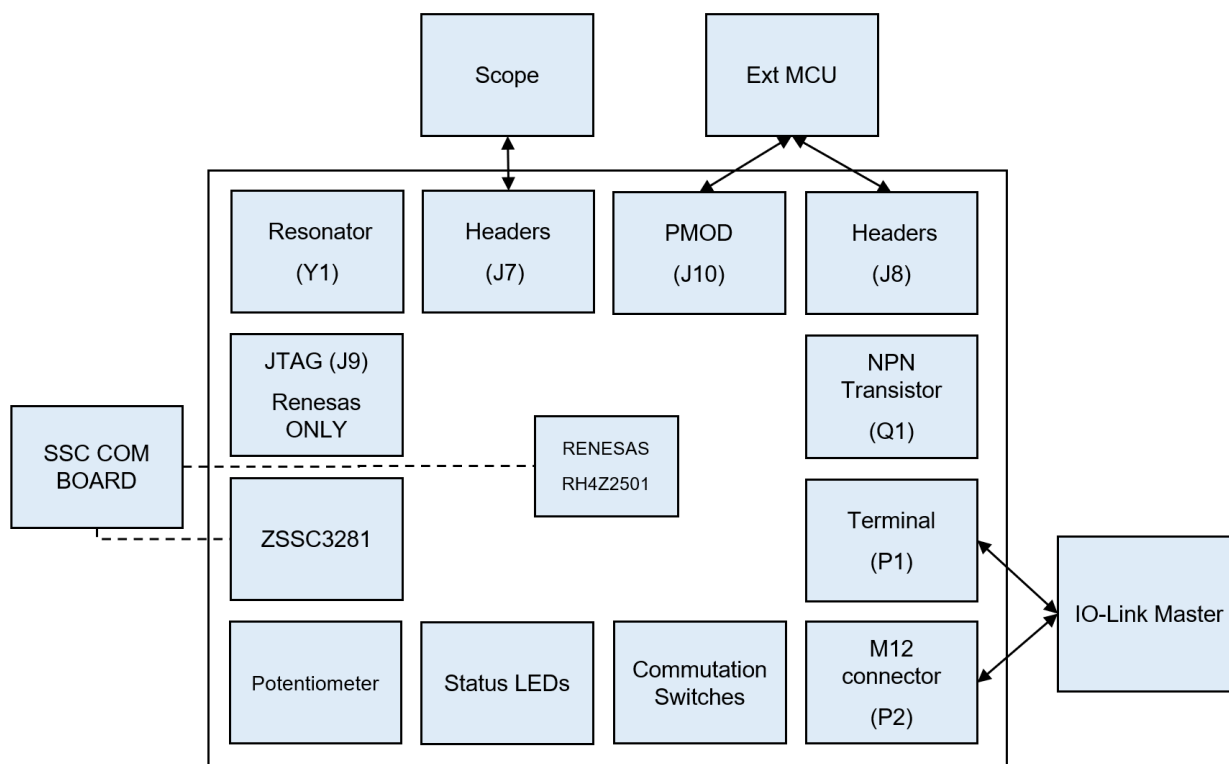
The RH4Z2501-KIT integrates all the necessary components to quickly evaluate the IO-Link Fieldbus technology.



Do **NOT** close J2 when using the SSC Communication Board at the same time as powering the board via the IO-Link line!

2. Getting Started

2.1 System Block Diagram



2.2 Default Board Configuration

Jumper/Switch	Default position
J1	LDO (J1_2-3)
J5	open
J2	open
J4	open
J6	open
SW1	ZSSC328x position
SW2	ZSSC328x position
SW3	ZSSC328x position
SW4	Com B position
SW5	ZSSC328x position
SW7	COM3

3. RH4Z2501-KIT Components

3.1 Power Requirements

3.1.1 Power Supply Options

3.1.1.1 Option 1: P2 Connector

P2 is a male 4-pin M12-A-coded connector. It enables an easy connection between the RH4Z2501-KIT and an IO-Link Master.

If powering RH4Z2501-KIT from the IO-Link Master:

- Set J1 to position LDO if you want to use the internal LDO to regulate the voltage
- Set J1 to position NPN if you want to use the internal external NPN transistor to regulate the voltage

3.1.1.2 Option 2: P1 Connector

The P2 connector signals are also accessible from P1.

3.1.1.3 Option 3: J3 Comm Board Connector

The SSCCOMMBBOARDV4P1C can power the RH4Z2501-KIT via J3_3 (KS5V).

- Close J2 to enable the 5V signal to supply the transceiver

Be aware that some OWI commands need to be executed in order to enable the supply. The PSU can also be enabled via the GUI.

3.1.1.4 Option 4: J7 RH4Z2501

J7 can directly supply the 5V to the RH4Z2501 via J7_1.

3.1.1.5 Option 5: J8 Ext uC Connector

J8 can directly supply the 5V to the RH4Z2501 via J8_1.

3.1.2 Voltage regulation Options

The RH4Z2501-KIT enables 2 methods to regulate the voltage supplied from the IO-Link Master:

3.1.2.1 Option 1: Integrated transceiver LDOs

Set J1 to position "LDO" if you want to use the internal PHY LDO to regulate the voltage.

3.1.2.2 Option 2: External NPN Transistor

Set J1 to position "NPN" if you wish to improve the thermal performance of the device and allow a higher current supply.

3.1.3 IO Voltage operation

Close J5 if you wish to operate the IOs under a 5V logic level. The PHY digital IOs will operate at 3V3 if left open.

3.2 Signal Sensor Conditioner: ZSSC3281

3.2.1 Enable I2C communication

Close J4 and J6 to enable the SSC Comm Board to establish an I2C communication with the ZSSC3281. This interface is used to configure the device via a GUI.

3.2.2 JTAG/SWD Connector

Use J9 to connect a J-Link probe to update the firmware running on the ZSSC3281. (Only Renesas internally)

3.2.3 AFE circuit

The bridge circuit attached to the SSC'AFE is composed of a potentiometer R9 and 4 resistors. This simple configuration is implemented to provide an easy way to act on the input signal of the SSC.

3.2.4 Oscillator

The ZSSC3281 is equipped with an on-chip oscillator. As an alternative, it is also possible to use Y1 as external resonator to achieve a better clock precision. This selection is implemented in its firmware and Y1 is used by default.

3.2.5 COM selection

SW7 enables the IO-Link baudrate selection at startup. Make sure to press the reset switch SW6 after each COM update.

3.3 Commutation Switches

The 5 onboard 3 position switches are used to select the target (ZSSC3281, SSCCOMMBBOARDV4P1C or ext MCU) the RH4Z2501 will communicate with.

3.3.1 SW1 – RxD Signal selection

This switch enables the path between RH4Z2501 pin RxD:

- GPIO3 of ZSSC3281
- PE4 of SSCCOMMBBOARDV4P1C
- Pin 4 of J8 (PMOD)

3.3.2 SW2 – TxD Signal selection

This switch enables the path between RH4Z2501 pin TxD:

- GPIO2 of ZSSC3281
- PE5 of SSCCOMMBBOARDV4P1C
- Pin 5 of J8 (PMOD)

3.3.3 SW3 – TxEN Signal selection

This switch enables the path between RH4Z2501 pin TxEN:

- GPIO11 of ZSSC3281
- PE6 of SSCCOMMBBOARDV4P1C
- Pin 6 of J8 (PMOD)

3.3.4 SW4 – OWI/D Signal selection

This switch enables the path between RH4Z2501 pin OWI/D:

- GPIO7 of ZSSC3281
- OWI of SSCCOMMBBOARDV4P1C
- Pin 7 of J8 (PMOD)

3.3.5 SW1 – /WU Signal selection

This switch enables the path between RH4Z2501 pin /WU:

- GPIO10 of ZSSC3281
- PE7 of SSCCOMMBBOARDV4P1C
- Pin 8 of J8 (PMOD)

3.4 LEDs

3.4.1 Power status

LED3 is powered from the 3V3 power rail regulated by the RH4Z2501. It therefore signals if the IO-Link transceiver is powered.

3.4.2 SSC status

LED1 connected to GPIO1 of ZSSC3281 signals if the SSC is operating.

3.4.3 IO-link communication status

LED2 is used to easily visualize the status of the C/Q line. Its signal is simply regulated by NPN transistor Q2 and its voltage divider.

Revision History

Rev.	Date	Description	
		Page	Summary
0.1	01/12/2021		Preliminary
0.2	02/06/2022		Modification for HW v2
1.0	09/08/2022		Minor modifications
1.1	19/12/2022		Modification for HW v3

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity.

Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

Notice

1. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation or any other use of the circuits, software, and information in the design of your product or system. Renesas Electronics disclaims any and all liability for any losses and damages incurred by you or third parties arising from the use of these circuits, software, or information.
2. Renesas Electronics hereby expressly disclaims any warranties against and liability for infringement or any other claims involving patents, copyrights, or other intellectual property rights of third parties, by or arising from the use of Renesas Electronics products or technical information described in this document, including but not limited to, the product data, drawings, charts, programs, algorithms, and application examples.
3. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
4. You shall be responsible for determining what licenses are required from any third parties, and obtaining such licenses for the lawful import, export, manufacture, sales, utilization, distribution or other disposal of any products incorporating Renesas Electronics products, if required.
5. You shall not alter, modify, copy, or reverse engineer any Renesas Electronics product, whether in whole or in part. Renesas Electronics disclaims any and all liability for any losses or damages incurred by you or third parties arising from such alteration, modification, copying or reverse engineering.
6. Renesas Electronics products are classified according to the following two quality grades: "Standard" and "High Quality". The intended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below.

"Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; industrial robots; etc.

"High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control (traffic lights); large-scale communication equipment; key financial terminal systems; safety control equipment; etc.

Unless expressly designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not intended or authorized for use in products or systems that may pose a direct threat to human life or bodily injury (artificial life support devices or systems; surgical implantations; etc.), or may cause serious property damage (space system; undersea repeaters; nuclear power control systems; aircraft control systems; key plant systems; military equipment; etc.). Renesas Electronics disclaims any and all liability for any damages or losses incurred by you or any third parties arising from the use of any Renesas Electronics product that is inconsistent with any Renesas Electronics data sheet, user's manual or other Renesas Electronics document.

7. No semiconductor product is absolutely secure. Notwithstanding any security measures or features that may be implemented in Renesas Electronics hardware or software products, Renesas Electronics shall have absolutely no liability arising out of any vulnerability or security breach, including but not limited to any unauthorized access to or use of a Renesas Electronics product or a system that uses a Renesas Electronics product. RENESAS ELECTRONICS DOES NOT WARRANT OR GUARANTEE THAT RENESAS ELECTRONICS PRODUCTS, OR ANY SYSTEMS CREATED USING RENESAS ELECTRONICS PRODUCTS WILL BE INVULNERABLE OR FREE FROM CORRUPTION, ATTACK, VIRUSES, INTERFERENCE, HACKING, DATA LOSS OR THEFT, OR OTHER SECURITY INTRUSION ("Vulnerability Issues"). RENESAS ELECTRONICS DISCLAIMS ANY AND ALL RESPONSIBILITY OR LIABILITY ARISING FROM OR RELATED TO ANY VULNERABILITY ISSUES. FURTHERMORE, TO THE EXTENT PERMITTED BY APPLICABLE LAW, RENESAS ELECTRONICS DISCLAIMS ANY AND ALL WARRANTIES, EXPRESS OR IMPLIED, WITH RESPECT TO THIS DOCUMENT AND ANY RELATED OR ACCOMPANYING SOFTWARE OR HARDWARE, INCLUDING BUT NOT LIMITED TO THE IMPLIED WARRANTIES OF MERCHANTABILITY, OR FITNESS FOR A PARTICULAR PURPOSE.
8. When using Renesas Electronics products, refer to the latest product information (data sheets, user's manuals, application notes, "General Notes for Handling and Using Semiconductor Devices" in the reliability handbook, etc.), and ensure that usage conditions are within the ranges specified by Renesas Electronics with respect to maximum ratings, operating power supply voltage range, heat dissipation characteristics, installation, etc. Renesas Electronics disclaims any and all liability for any malfunctions, failure or accident arising out of the use of Renesas Electronics products outside of such specified ranges.
9. Although Renesas Electronics endeavors to improve the quality and reliability of Renesas Electronics products, semiconductor products have specific characteristics, such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Unless designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not subject to radiation resistance design. You are responsible for implementing safety measures to guard against the possibility of bodily injury, injury or damage caused by fire, and/or danger to the public in the event of a failure or malfunction of Renesas Electronics products, such as safety design for hardware and software, including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult and impractical, you are responsible for evaluating the safety of the final products or systems manufactured by you.
10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. You are responsible for carefully and sufficiently investigating applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive, and using Renesas Electronics products in compliance with all these applicable laws and regulations. Renesas Electronics disclaims any and all liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
11. Renesas Electronics products and technologies shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations. You shall comply with any applicable export control laws and regulations promulgated and administered by the governments of any countries asserting jurisdiction over the parties or transactions.
12. It is the responsibility of the buyer or distributor of Renesas Electronics products, or any other party who distributes, disposes of, or otherwise sells or transfers the product to a third party, to notify such third party in advance of the contents and conditions set forth in this document.
13. This document shall not be reprinted, reproduced or duplicated in any form, in whole or in part, without prior written consent of Renesas Electronics.
14. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products.

(Note1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its directly or indirectly controlled subsidiaries.

(Note2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

(Rev.5.0-1 October 2020)

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,
Koto-ku, Tokyo 135-0061, Japan
www.renesas.com

Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.

Contact information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit:
www.renesas.com/contact/.